

### MICRO SATA RECEPTACLE

#### 1.0 SCOPE

This Product Specification covers the performance requirements of the Micro Serial ATA / High Speed Serialized device receptacle connector.

#### 2.0 PRODUCT DESCRIPTION

#### 2.1 PRODUCT NAME AND SERIES NUMBER(S)

#### Product Name

MICRO SATA RECEPTACLE, VERTICAL SMT

Part Number

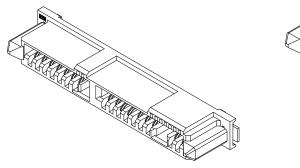
78500-0001

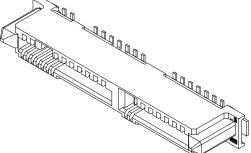
### 2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS

See Sales Drawing SD-78500-001 for information on dimensions, materials, platings and markings.

### 2.3 SAFETY AGENCY APPROVALS

UL FILE	: E29179
CSA	: 1699020 (LR19980)





TENTATIVE RELEASE: THIS SPECIFICATION IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. PRELIMINARY TEST DATA MAY EXIST, BUT THIS SPECIFICATION IS SUBJECT TO CHANGE BASED ON THE RESULTS OF ADDITIONAL TESTING AND EVALUATION

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4	EC No: S2010-0821	V	ERTICAL SMT		<b>1</b> of <b>9</b>
4	<u>DATE:</u> 2010/03/29	1.8	INCH SSD/HDD		1 01 9
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### 3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

The following documents form a part of this specification to the extend specified herewith. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In addition, in event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

SATA Specification

### 4.0 RATINGS

#### 4.1 VOLTAGE 30 Volts Max

SU VUILS MAX

4.2 CURRENT 1.5 Amps DC or AC (RMS) Max @ 60 Hz

### 4.3 TEMPERATURE

Operating: - 0°C to + 55°C Non Operating: - 40°C to + 85°C

**4.4 HUMIDITY** 20% - 80%

20% - 80%

#### 4.5 ATMOSPHERIC PRESSURE 650mm – 800mm Hg

#### 5.0 PERFORMANCE

#### 5.1 ELECTRICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
1	Low Level Contact Resistance (LLCR)	Subject mated contacts assembled in housing to <b>20</b> mV maximum open circuit at <b>100</b> mA maximum. (EIA 364-23)	<b>30</b> mΩ MAXIMUM [Initial] <b>15</b> mΩ MAXIMUM [Delta change from Initial]
2	Insulation Resistance	Apply a voltage of <b>500</b> VDC for <b>1</b> minute between adjacent terminals. Measure the insulation resistance for mated and unmated connectors (EIA 364-21)	<b>1000</b> ΜΩ ΜΙΝΙΜUΜ

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3	Contact Current Rating (Power Segment)	<ul> <li>Mount connector to a test PCB with ½ oz copper layer.</li> <li>Wire two adjacent pins in parallel for supply (or the minimum number required by the connector type)</li> <li>Wire two adjacent pins in parallel for return (or the minimum number required by the connector type)</li> <li>Apply a DC current of <b>two</b> times the current rating per contact to the supply pins, returning through the return pins.</li> <li>Record temperature rise when thermal equilibrium is reached.</li> </ul>	<ul> <li>1.5 A per pin MINIMUM</li> <li>Temperature rise shall not exceed 30°C at any point in the connector when contacts are powered</li> <li>Still Air at Ambient temperature 25°C</li> </ul>		
4	Dielectric Withstanding Voltage	Apply a voltage of <b>500</b> VAC for <b>1</b> minute between adjacent terminals of mated and unmated connectors. (EIA 364-20 Method B)	No breakdown		

### 5.2 MECHANICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
5	Connector Insertion and Removal Forces	Mate and Unmate connector assemblies at a rate of <b>12.5</b> mm per minute. (EIA 364-13)	MAXIMUM Insertion Force: 20 N & <u>MINIMUM Removal Force</u> : 2.5 N <u>MAXIMUM Removal Force</u> 20N [Initial and after 500 cycles]
6	Durability	<b>500</b> cycles for backplane/blindmate application. All at a maximum rate of <b>200</b> cycles per hour. (EIA 364-09)	No Physical damage Meet requirements of additional tests as specified in the test sequence in Section 7.0

REVISION: 4	ECR/ECN INFORMATION: EC No: <b>\$2010-0821</b> DATE: <b>2010/03/29</b>	IITLE:       MICRO SATA RECEPTACLE         VERTICAL SMT       1.8 INCH SSD/HDD		<u>SHEET No.</u> <b>3</b> of <b>9</b>
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7	7	Component Retention Force	Apply axial pull out force on solder tab in the housing at a rate of <b>25.4</b> mm per minute.	Terminal 3.50 N MINIMUM retention force Solder Tab 3.50 N MINIMUM retention force
٤	8	Physical Shock	Subject mated connector to <b>30</b> g's half-sine shock pulses of <b>11</b> msec duration. Three shocks in each direction applied along three mutually perpendicular planes for a total of <b>18</b> shocks. (EIA 364-27 Condition H)	No Physical damage No discontinuities of 1 μs or longer duration
ę	9 1	Random Vibration	Subject mated connector to <b>5.35</b> g's RMS. <b>30</b> minutes in each of the three mutually perpendicular planes. (EIA 364-28 Condition V Test letter A)	No discontinuities of 1 μs or longer duration

### 5.3 ENVIRONMENTAL REQUIREMENTS

ITEN	I DESCRIPTION	TEST CONDITION		R	EQUIREME	NT
Resistance to     Refer to Section 9.0 for soldering profile     No damage in ap		humidity of 40°C at 95% R	H for <b>96</b> hours.	Mee additiona	t requiremen al tests as sp	nts of becified in ce in
		age in appea connector	arance of			
12	Solderability	Solder Time : $3 \pm 0.5$ secor Solder Temperature : 260 =		95% MIN Solder coverage		ge
13	Temperature Life	Subject mated connector to temperature life at <b>+85</b> °C for <b>500</b> hours. (EIA 364-17 Test Condition III Method A)		Physical dan t requiremen al tests as sp test sequend Section 7.0	nts of becified in ce in	
VISION:         ECR/ECN INFORMATION:           EC No:         \$2010-0821           DATE:         2010/03/29		V	SATA REC ERTICAL S INCH SSD/	МТ	LE	<u>SHEET</u>
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				No Physical damage
	14	Thermal Shock	Subject connector to <b>10</b> cycles between - <b>55</b> °C and <b>+85</b> °C. (EIA 364-32 Test Condition I)	Meet requirements of additional tests as specified in the test sequence in Section 7.0
			Half of the samples are exposed <b>unmated</b> for <b>7</b> days, then <b>mated</b> for the	No Physical damage
	15	Mixed Flowing Gas	remaining 7 days. The other half of the	Meet requirements of
			samples <b>mated</b> for full <b>14</b> days test period.	additional tests as specified in the test sequence in
			(EIA 364-65, Class 2A)	Section 7.0

#### 6.0 PACKAGING

Refer to Sales Drawing SD-78500-001 for packing details.

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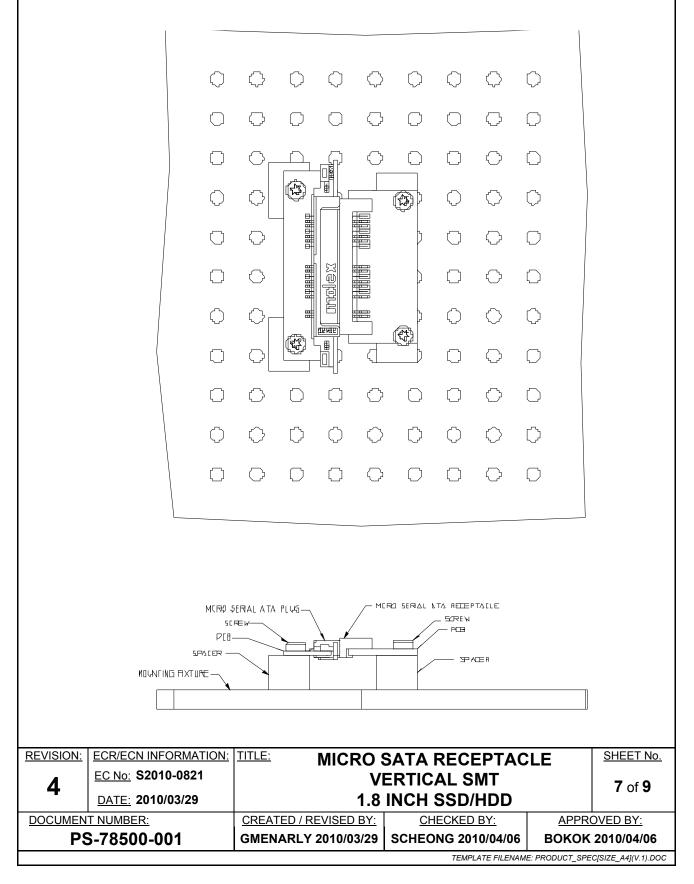
### 7.0 TEST SEQUENCES

Test Group →	Α	в	С	D	Е	F	G	н
Test or Examination <b>↓</b>								
Examination of the connector(s)	1, 5	1, 9	1, 8	1, 8	1, 7	1	1, 5	
Low Level Contact Resistance (LLCR)	2, 4	3, 7	2, 4, 6		4, 6			
Insulation Resistance				2, 6				
Dielectric Withstanding Voltage				3, 7				
Current Rating			7					
Insertion Force		2					2	
Removal Force		8					4	
Durability	3	4 <sup>(a)</sup>			2 <sup>(a)</sup>		3 <sup>(b)</sup>	
Physical Shock		6						
Vibration		5						
Humidity				5				
Temperature Life			3					
Reseating (manually unplug/plug three times)			5		5			
Mixed Flowing Gas					3			
Thermal Shock				4				
Resistance to Soldering Heat						3		
Component Retention Force						2, 4		
Solderability								1
<ul> <li>Note – <ul> <li>(a) Preconditioning, 20 cycles 1</li> <li>durability cycles requirements</li> <li>of 200 cycles per hour.</li> </ul> </li> <li>(b) Backplane Receptacle – 50 <ul> <li>Insertion/Removal force of</li> <li>cycles as well. The insertion</li> <li>per hour.</li> </ul> </li> </ul>	nt. The 0cycles, Cable	insertio Cable Power	n and rei Power or Recepta	moval o Signal cles to	cycle is Recept be me	at the acles - easured	maximu - 50cycle 1 for 1 <sup>st</sup>	m rate es, to 5 <sup>th</sup>
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### 8.0 VIBRATION/SHOCK TEST SET-UP (FOR REFERENCE ONLY)

Micro SATA plug with backplane receptacle





#### 8.0 VIBRATION/SHOCK TEST SET-UP (FOR REFERENCE ONLY)

Micro SATA plug with cable receptacle

